LAND GRID ARRAY SEMICONDUCTOR DEVICE PACKAGES, ASSEMBLIES INCLUDING SAME, AND METHODS OF FABRICATION

ABSTRACT OF THE DISCLOSURE

A semiconductor device package includes a land grid array package. At least one semiconductor die is mounted to an interposer substrate, with bond pads of the semiconductor die connected to terminal pads on the same side of the interposer substrate as the at least one semiconductor die. Terminal pads of the interposer substrate may be electrically connected to either or both of a peripheral array pattern of lands and to a central, two-dimensional array pattern of pads, both array patterns located on the opposing side of the interposer substrate from the at least one semiconductor die. Additional components, active, passive or both, may be connected to pads of the two-dimensional array to provide a system-in-a-package. Lead fingers of a lead frame may be superimposed on the opposing side of the interposer substrate, bonded directly to the land grid array land and wire bonded to pads as desired for repair or to ease routing problems on the interposer. The land grid array package may be mounted to a carrier substrate, and the lands wire bonded to conductive pads on the carrier substrate. Methods of fabrication are also disclosed.

[FIG. 6]